

TSMC-00-234



October 20, 2004

To: Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/038,388 01/03/02 |
Hsiu-Mei Yu et al.
ELASTOMER PLATING MASK SEALED WAFER
LEVEL PACKAGE METHOD
| _____ |

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
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P.O. Box 1450, Alexandria, VA 22313-1450, on October 28, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

 10/25/04

TSMC-00-234

U.S. Patent 5,937,320 to Andricacos et al., "Barrier Layers for Electroplated SNPB Eutectic Solder Joints," discloses a means of fabricating a reliable flip-chip structure for low-temperature joining.

U.S. Patent 6,103,552 to Lin, "Wafer Scale Packaging Scheme," describes a process and a package for achieving wafer scale packaging.

Sincerely,

A handwritten signature in black ink, appearing to be 'SBA', written over a horizontal line.

Stephen B. Ackerman,
Reg. No. 37761

INFORMATION DISCLOSURE CITATION IN AN APPLICATION

(Use several sheets if necessary)

OCT 27 2004

Docket Number (Optional)

Application Number

Tsmc - 00 - 234

10/038, 388

Applicant

Hsia-Mei Yu et al.

Filing Date

01/03/02

Group Art Unit

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILED DATE IF APPROPRIATE
	5937320	8/10/99	Andricacos et al.	438	614	4/8/98
	6103552	8/15/00	Lin	438	113	8/10/98

FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
					YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Portion of Pages, Etc.)

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.